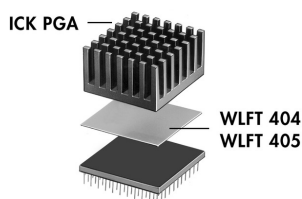


Data sheet Product ICK PGA 6 x 6 x 14



Heatsinks and active heatsinks for processors>Heatsinks for PGA
 14 x 14 x 14 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	14 mm
height:	14 mm
plate thickness:	2.5 mm
length:	14 mm
thermal resistance:	20 - 8 K/W
dissipation loss:	6.4 W
surface:	black anodised

Technical Drawing

